**THAPAR INSTITUTE OF ENGINEERING & TECHNOLOGY, PATIALA**

(Deemed to be University)

CENTRE FOR INDUSTRIAL LIAISON AND PLACEMENT

Dated: 20.11.2024

CAMPUS INTERVIEWS

1. Name of the Organization: **Amazon**

**(www.amazon.com)**

**(Profile –SDE role)**

Branches of Engineering: BE –CS (All branches) /EE /EEC

Eligibility Criteria Present CGPA 6.50

(No active backlogs)

Process of Interviews: Short listing based upon your details

Online Assessment

Two rounds of Interview

2. **Virtual PPT and Online test on \_\_\_\_\_November, 2024 at 3.00 PM**

**Virtual Interviews on \_\_\_\_\_November, 2024 at**

3 **Submit the details & resume as per organizational format to the below TIET Google link by 22nd November, 2024 by 10.00 AM**

[**https://forms.gle/jyn1fG1oGbZvZfdG8**](https://forms.gle/jyn1fG1oGbZvZfdG8)

4. CTC ~ Stipend- 1,10,000 per month and $400 relocation allowance

LOI will be provided based on performance, compensation will be shared at the time of LOI. Ball park number for this year is **Base pay -19 LPA** Signon bonus year 1 - 6 LPA, Sign on bounce year 2- 5 LPA, RSU – 10L worth vesting over period of 4 years

5. Job location:  Bangalore, Hyderabad, Chennai

Note- Internship & FTE (subjected to performance during internship)

( H.S. Bawa )

Head CILP

CC: HEIED/HECED - for kind information please